

# Simon S Ang

## List of Publications by Year in descending order

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41  
papers

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citations

1163117

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1199594

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all docs

41  
docs citations

41  
times ranked

414  
citing authors

#	ARTICLE	IF	CITATIONS
1	Investigation of Low-Profile, High-Performance 62-mm SiC Power Module Package. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2021, 9, 3850-3866.	5.4	16
2	A High-Input Voltage Two-Phase Series-Capacitor DC-DC Buck Converter. Journal of Electrical and Computer Engineering, 2020, 2020, 1-15.	0.9	4
3	Submicron guided-mode-resonance filter for wide bandwidth near-infrared polarizer. Optical Engineering, 2020, 59, 1.	1.0	0
4	Design and Analysis of a New GaN-Based AC/DC Converter for Battery Charging Application. IEEE Transactions on Industry Applications, 2019, 55, 4044-4052.	4.9	23
5	High-Frequency Transformer Review and Design for Low-Power Solid-State Transformer Topology. , 2019, , .		20
6	A Module-Level Spring-Interconnected Stack Power Module. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 88-95.	2.5	17
7	Hepta-Band Coupled-Fed Loop Antenna For LTE/WWAN Unbroken Metal-Rimmed Smartphone Applications. IEEE Antennas and Wireless Propagation Letters, 2018, 17, 311-314.	4.0	52
8	Design and evaluation of a high-current gate driver circuit for six paralleled 1.2kV 36A SiC MOSFETs. , 2018, , .		2
9	Investigation of a new GaN AC/DC topology for battery charging application. , 2018, , .		3
10	A Single-Step Bidirectional Switch Commutation Strategy for PWM Controlled AC/DC Resonant Converters. , 2018, , .		0
11	Packaging Architectures for Silicon Carbide Power Electronic Modules. , 2018, , .		13
12	Design and analysis of a new GaN-based AC/DC topology for battery charging application. , 2018, , .		8
13	Investigations of low temperature co-fired ceramic heat spreading interposer for the thermal management of three-dimensional packages. , 2018, , .		4
14	Effects of parasitic parameters on electromagnetic interference of power electronic modules. , 2017, , .		11
15	TMS320F28335 DSP programming using MATLAB Simulink embedded coder: Techniques and advancements. , 2017, , .		15
16	Impact of nano-diamond composites on low-temperature co-fired ceramic interposer for wide bandgap power electronic module packages. , 2016, , .		5
17	Structure design and process improvement of planar oxygen sensor. , 2016, , .		0
18	Electromagnetic Interference Simulations for Wide-Bandgap Power Electronic Modules. IEEE Journal of Emerging and Selected Topics in Power Electronics, 2016, 4, 757-766.	5.4	42

#	ARTICLE	IF	CITATIONS
19	Thermal simulation of gallium nitride power packages. , 2016, , .		1
20	Electromagnetic interference simulations of power electronic modules. , 2015, , .		10
21	Simulation of a power package with underfill resin and silicon gel. , 2015, , .		0
22	A new curvature-compensated, high-PSRR CMOS bandgap reference. Analog Integrated Circuits and Signal Processing, 2015, 82, 675-682.	1.4	4
23	A silicon carbide fault current limiter for distribution systems. , 2014, , .		8
24	Realization of a Modular Indirect Matrix Converter System Using Normally Off SiC JFETs. IEEE Transactions on Power Electronics, 2014, 29, 2574-2583.	7.9	23
25	Quasi-Symmetric Wheatstone Bridge Zinc Oxide Nanorod UV Detectors. IEEE Sensors Journal, 2014, 14, 3310-3318.	4.7	8
26	Realization of a SiC module-based indirect matrix converter with minimum parasitic inductances. , 2014, , .		6
27	Design philosophy of hysteretic controller for DC-DC switching converters. , 2013, , .		1
28	A nano-composite polyamide imide passivation for 10 kV power electronics modules. , 2012, , .		4
29	A 4 kV Silicon Carbide solid-state fault current limiter. , 2012, , .		13
30	Transient Liquid Phase Die Attach for High-Temperature Silicon Carbide Power Devices. IEEE Transactions on Components and Packaging Technologies, 2010, 33, 563-570.	1.3	98
31	A RGB-driver for LED display panels. , 2010, , .		12
32	A solid state fault current limiter control algorithm. , 2010, , .		3
33	Tungsten Carbide as a Diffusion Barrier on Silicon Nitride Active- Metal-Brazed Substrates for Silicon Carbide Power Devices. Journal of Electronic Packaging, Transactions of the ASME, 2009, 131, .	1.8	8
34	Packaging and characterization of silicon carbide thyristor power modules. , 2009, , .		3
35	A built-in self-test high-current LED driver. , 2009, , .		1
36	An automatic fluidic system for the rapid detection of soil nutrients. , 2008, , .		4

#	ARTICLE	IF	CITATIONS
37	Development of a Polypyrrole Modified Gold Microelectrode for Soil Nitrate Detection. , 2007, , .		1
38	Study on the polishing mechanism of low temperature co-fired ceramic for microsystem application(Surface and edge finishing). Proceedings of International Conference on Leading Edge Manufacturing in 21st Century LEM21, 2005, 2005.3, 1171-1176.	0.0	0
39	Impact of residual by-products from tungsten film deposition on process integration due to nonuniformity of the tungsten film. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2002, 20, 934-940.	2.1	0
40	Evaluation of Contact and Via Step Coverage Using a Novel Two-Step Titanium Nitride Barrier Deposition Process. Materials Research Society Symposia Proceedings, 2002, 716, 12101.	0.1	3
41	Study of the Microstructure of Amorphous Germanium Alloys Using AFM and SAXS. Materials Research Society Symposia Proceedings, 1995, 377, 197.	0.1	0